

Change the title to read: --A METHOD FOR HANDLING INTEGRATED CIRCUIT DIE--.

Please replace the paragraph beginning on page 4, line 8 and ending on page 4, line 18 with the following amended paragraph marked up to show changes made relative to the immediate prior version:

The clip 300 includes a main body 302 which may take the form of a generally planar rectangular prism. The clip 300 also includes legs 304 which extend downwardly and somewhat outwardly from opposed ends 306 of the main body 302 of the clip 300. (To simplify the drawing, the legs 304 are not shown in FIG. 4.) The clip 300 further includes a pad 308 mounted on an underside 310 of the main body 302. The pad 308 may be formed of a relatively soft and heat-resistant material. For example, the pad 308 may be formed of a suitable polymer such as silicone, polyimide or fluoropolymer sponge (e.g., a polytetrafluoroethylene (PTFE) sponge). The pad 308 may be somewhat smaller in horizontal extent than the main body 302. The main body 302 and legs 304 of the clip 306 300 may be formed integrally of a suitable metal having a degree of resilience, such as stainless steel, iron alloy, copper alloy or aluminum.

Please replace the paragraph beginning on page 5, line 1 and ending on page 5, line 8 with the following amended paragraph marked up to show changes made relative to the immediate prior version:

The picking up of the clip 300 by the chuck 200 may be performed by bringing the lower surface of the main section 202 of the chuck 200 into contact with the upper surface of the main body 302 of the clip 300, with the vacuum aperture 210 of the chuck 200 in vertical alignment with the vacuum aperture 312 of the clip 300. The tips 208 of the fingers 204 of the chuck 200 may be moved toward each other so that each tip 208 engages a leg 304 of the clip 300. In this way the chuck 200 may grip the clip 300. The chuck 200 may then be raised to pick up the clip 300. FIG. 5 shows the chuck 200 holding the clip 300 after picking up the clip 300.